

**Amendments to the Claims:**

This listing of claims will replace all prior versions, and listings, of claims in the application:

**Listing of Claims:**

1. (currently amended) A polishing apparatus for performing a polishing operation comprising:

a polishing plate provided with an abrasive cloth;

a chuck for holding a polishing target material to bring the polishing target material into contact with the abrasive cloth;

a head body fixed to a rotary drive shaft having reciprocal movement in a plane, for holding and rotatably driving the chuck;

and a retainer ring supported by the head body in a periphery of the chuck,

the polishing target material being polished by the abrasive cloth by a relative motion of the polishing plate and the chuck,

characterized in that the polishing apparatus includes:

supporting means for supporting the retainer ring and the chuck respectively to the head main body so that the retainer ring and the chuck can be moved in a direction of the rotary drive shaft and in a direction perpendicular to the direction parallel to the reciprocal movement of the rotary drive shaft independently of each other; and

means for restricting movements of the retainer ring and the chuck so as to maintain a fluctuation of the size of a gap that is perpendicular to the direction parallel to the plane of the reciprocal movement of the rotary drive shaft between the retainer ring and the chuck within a predetermined range during the polishing operation.

2. (currently amended) A polishing apparatus according to claim 1, characterized in that the retainer ring is movable perpendicular to the in the vertical direction of the rotary drive shaft with respect to the chuck.

3. (currently amended) The polishing apparatus according to claim 1, characterized in that one or a plurality of clearances to facilitate anthe oscillation are provided.

4. (cancelled)

5. (previously amended) The polishing apparatus according to claim 1, characterized in that the range of the gap is between 0.5mm and 2.0mm.

6. (previously amended) The polishing apparatus according to claim 5, characterized in that the distance between the center of the chuck and the center of the polishing target material is no more than 0.5mm.

7. (previously amended) The polishing apparatus according to claim 1, characterized in that the retainer ring is rotatable with respect to the chuck.

Claims 8-10 (cancelled)